



MS-30PLUS

Product description

MS-30PLUS is a high elastic, solvent and water-free, universal parquet adhesive. Suitable for bonding engineered and solid parquet with tongue and groove onto suitable indoor subfloors.

Properties

- Flexible
- Very low emission, EC1+ certified
- Ready to use
- Solvent-free
- Isocyanate-free
- Contains no water
- Easy to tool
- Suitable for underfloor heating
- Elastic adhesive according to ISO17178



Applications

- MS-30PLUS is a parquet adhesive suitable for bonding of both engineered and solid parquet with tooth and groove.
- Solid parquet with a maximum width of 190mm and a minimal thickness of 16mm
- Engineered parquet with a maximum width of 280mm and a minimal thickness of 16mm

Technical data

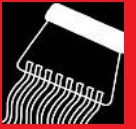
Base		Silane terminated SMX polymer
Consistency		Paste
Curing system		Chemical curing
Density		ca. 1,73 g/ml
Open time		25 - 30 minutes
Can be loaded after		At least 3 hours
Consumption		Depending on the surface and trowel Trowel B3: 750 - 1000 g/m ² Trowel B11: 1000 - 1400 g/m ²
Shear strength	ISO 17178	At least 1,50 N/mm ²
Application temperature		15°C - 25°C
Temperature resistance		-40°C → +90°C
Paintable after		At least 16 hours
Sandable after		At least 16 hours
Adjustable until		25 - 30 minutes

Footnote: evaporation time, open time and curing speed may vary depending on environmental factors such as temperature, moisture, and type of substrates.

Substrates

- Substrate condition
MS-30PLUS should be applied on a flat, rigid, clean, permanently dry, dust and grease free surface which do not contain any loose parts, paint, wax, oil or other contaminants. Irregularities such as remaining concrete leveling, old adhesives may adversely affect adhesion. These need preferably to be removed mechanically for example by sanding or blasting. Concrete surfaces that are not sturdy enough should preferably be removed.





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- **Substrate preparation**
Before installation of the parquet, the substrate should be checked to ensure it is suitable. Check the moisture content throughout the entire thickness of the substrate with a carbide or electric hygrometer. Note that an electric hygrometer only gives indicative values. The moisture content must correspond the recommendation of the floor manufacturer (generally max. 2% for sand cement substrates and max. 0,5% for anhydrite, measured with a carbide hygrometer. For substrates with underfloorheating the values are resp. max. 1,5% and 0,3%). Smooth surfaces like anhydrite should be roughened, and if necessary the top layer should be removed.
- **Substrate types**
Porous substrates like concrete and wood. The parquet flooring must be acclimatised for several days in the area where it is to be installed. Leave the parquet in its original packaging until installation to avoid any deformation. Check before installation that the moisture content of the wood is as recommended by the supplier, (generally 9% +/- 2%). If the humidity of the wood is more than 11% installation is not recommended. Allow a gap of 1 to 1,5 cm around the perimeter of the laid parquet, including any columns or structures, which penetrate the floor. We recommend a preliminary adhesion test on any substrate.

Application method

- **Application method**
MS-30PLUS should be acclimatised to room temperature before installation. Apply the adhesive by means of Soudal notched trowel B11 to the surface. Do not apply more to the surface than can be covered with parquet within 25 - 30 minutes. Slide the parquet onto the adhesive layer and tap into place or tamp down with a rubber hammer. A minimum of 80% contact coverage is required to ensure the adhesion of the parquet. If necessary load the parquet with weight. Wait At least 16 hours before sanding and finishing the parquet.
- **Cleaning method**
MS-30PLUS can be cleaned before curing from tools and material with Soudal Adhesive Remover, Soudal Swipex Wipes or white spirit. Cured product can only be removed mechanically.

Health- and Safety Recommendations

Take the usual labour hygiene into account. Consult the packaging label and safety data sheet for more information.

Packaging/Logistics

Packaging: Various sizes available. Please consult the product catalogue, the Soudal website or a Soudal representative.

Shelf life: Bucket: 9 months in unopened packaging in a cool and dry storage place at temperatures between +5°C and +25°C, Aluminum bag in cardboard box/ bucket: 18 months in unopened packaging in a cool and dry storage place at temperatures between +5°C and +25°C

Remarks

- Minimum temperature of the substrate should be at least 15°C.
- Do not apply the adhesive when the relative humidity is above 75%.
- Never install flooring on a substrate which contains too much moisture or on substrates with a higher humidity value than recommended by the wood supplier.
- Never install wood which is too dry (<7% humidity). It can expand at higher humidity and cause damage.
- Do not install if the walls and ceilings of the area are not dry (e.g. after plastering or painting etc.)
- MS-30PLUS should not be diluted.
- Never apply on a substrate which is not protected against rising damp. If necessary apply a moisture sealer such as Soudal EPR-31P Epoxy seal.

This technical data sheet replaces all previous versions. The directives contained in this documentation are the result of our experiments and of our experience and have been submitted in good faith. It is general in nature and does not constitute any liability. Because of the diversity of the materials and substrates and the great number of possible applications which are out of our control, we cannot accept any responsibility for the results obtained. Since the design, the quality of the substrate and processing conditions are beyond our control, no liability under this publication is accepted. It is the responsibility of the user to determine by his own tests whether the product is suitable for the application. In every case it is recommended to carry out preliminary experiments. The manufacturer reserves the right to modify products without prior notice.